

FQT1N60C N-Channel QFET[®] MOSFET 600V, 0.2 A, 11.5 Ω

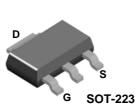
Description

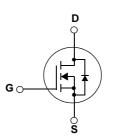
This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

March 2013

Features

- 0.2 A, 600 V, $R_{DS(on)}$ =9.3 $\Omega(V^{\circ}]$.)@V_{GS}=10 V, I_D=0.1 A
- Low Gate Charge (Typ. I È nC)
- Low C_{rss} (Typ. HĚ pF)
- 100% Avalanche Tested
- RoHS Compliant





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol		Parameter		FQT1N60C	Unit
V _{DSS}	Drain to Source Voltage			600	V
V _{GSS}	Gate to Source Voltage			±30	V
I _D	DrainCurrent	-Continuous (T _C = 25 ^o C)		0.2	A
	DrainCurrent	-Continuous (T _C = 100 ^o C)		0.12	A
I _{DM}	DrainCurrent	- Pulsed	0.8	А	
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	33	mJ
I _{AR}	Avalanche Current		(Note 1)	0.2	А
E _{AR}	Repetitive Avalanche Energy		(Note 1)	0.2	mJ
dv/dt	Peak Diode Recovery dv/d	Diode Recovery dv/dt (Note 3)		4.5	V/ns
P _D	Dower Dissinction	(T _C = 25°C)		2.1	W
	Power Dissipation	- Derate above 25ºC		0.02	W/ºC
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
TL	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

Thermal Characteristics

Symbol	Parameter	Min.	Max.	Unit
R_{\thetaJA}	Thermal Resistance, Junction to Ambient*	-	60	°C/W

* When mounted on the minimum pad size recommended (PCB Mount)

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	Device Marking Device Packa		Package		Reel Size	Таре	e Width		Quantit	y
	-		SOT-223		330mm	-	2mm 4000			•
Electrica	I Char	acteristics		J.				1		
Symbol		Parameter		Test Conditions			Min.	Тур.	Max.	Unit
Off Charac	teristic	S								
BV _{DSS}		Source Breakdown V	oltage I	lp = 250uA	$V_{00} = 0V T_{0}$	= 25°C	600	-	-	V
ΔBV_{DSS}		eakdown Voltage Temperature		$I_D = 250\mu A, V_{GS} = 0V, T_J = 25^{\circ}C$ $I_D = 250\mu A, Referenced to 25^{\circ}C$						-
$/ \Delta T_J$	Coeffici	•	1	I _D = 250μA,	Referenced t	to 25°C	-	0.6	-	V/°C
 	Zero Ga	ate Voltage Drain Curr	٩nt	V _{DS} = 600V	, V _{GS} = 0V		-	-	25	
DSS	2010 08	Zero Gate Voltage Drain Current			, T _C = 125°C		-	I	250	μA
I _{GSS}	Gate to Body Leakage Current			V _{GS} = ±30V	, V _{DS} = 0V		-	-	±100	nA
On Charac	toristic	e								
	Т			V - V		T	2.0		4.0	11
V _{GS(th)}		reshold Voltage rain to Source On Res		$V_{GS} = V_{DS},$			2.0	- 9.3	4.0 11.5	V Ω
R _{DS(on)}		d Transconductance		$\frac{V_{GS} = 10V}{V_{DS} = 40V},$	-		-		11.5	Ω S
9 _{FS}	FOIWard			v _{DS} - 40v,	I _D = 0.1A	(Note 4)	-	0.75	-	3
Dynamic C	haracte	eristics								
C _{iss}	Input Ca	put Capacitance utput Capacitance everse Transfer Capacitance otal Gate Charge at 10V ate to Source Gate Charge ate to Drain "Miller" Charge		$V_{DS} = 25V, V_{GS} = 0V$ f = 1MHz $V_{DS} = 480V, I_{D} = 1A$ $V_{GS} = 10V$ (Note 4, 5)			-	130	170	pF
C _{oss}	Output						-	19	25	pF
C _{rss}	-						-	3.5	6	pF
Q _q	Total Ga						-	4.8	6.2	nC
Q _{gs}	Gate to						-	0.7	-	nC
Q _{gd}	Gate to						-	2.7	-	nC
Desite la la sur a	0	(a.m.)				•				
Switching	1									1
t _{d(on)}		Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time		V_{DD} = 300V, I_D = 1A R _G = 25 Ω			-	7	24	ns
t _r							-	21	52	ns
t _{d(off)}							-	13	36	ns
t _f	Turn-Of	f Fall Time				(Note 4, 5)	-	27	64	ns
Drain-Sour	ce Dioc	de Characteristic	S							
I _S	Maximu	m Continuous Drain to	Source Diode	Forward Cu	rrent		-	-	0.2	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Fo		Irce Diode Forw				-	-	0.8	Α
V _{SD}	Drain to Source Diode Forward Voltage			V _{GS} = 0V, I _{SD} = 0.2A			-	-	1.4	V
t _{rr}	Reverse Recovery Time			$V_{GS} = 0V, I_{SD} = 1A$			-	190	-	ns
Q _{rr}	Reverse	Recovery Charge		$dI_F/dt = 100$		(Note 4)	-	0.53	-	μC

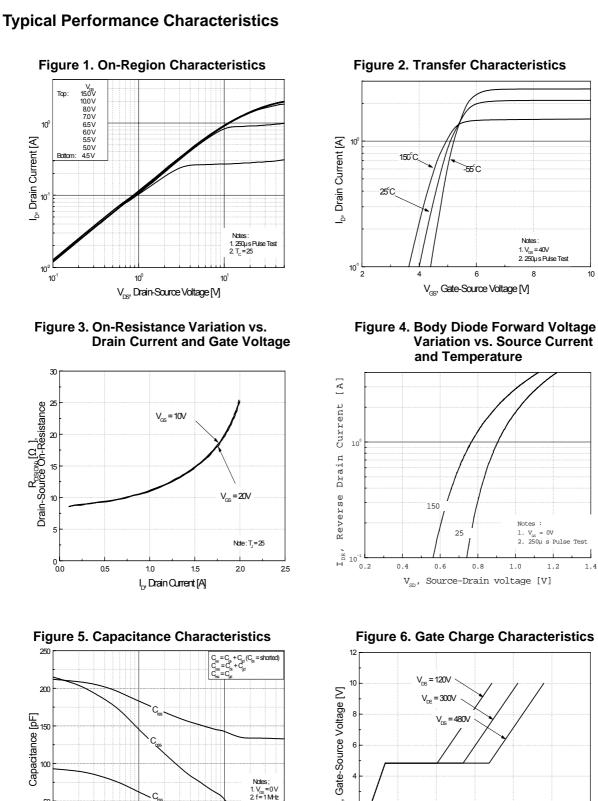


Figure 2. Transfer Characteristics

-55 C

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V_{cs}, Gate-Source Voltage [V]

150

0.6

V_{DS} = 120V

 $<_{\rm GS}$

3

0

0

V_{DS} = 300V

V_{DS} = 480V

25

0.8

Notes : 1. V_{DS} = 40V 2. 250µ s Pulse Test

10

8

Notes :

1.0

Note : I_b = 1A

3

Q_c, Total Gate Charge [nC]

 V_{∞} = 0V 250µ s Pulse Test

1.2

1.4



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10⁰

V_{DS}, Drain-Source Voltage [V]

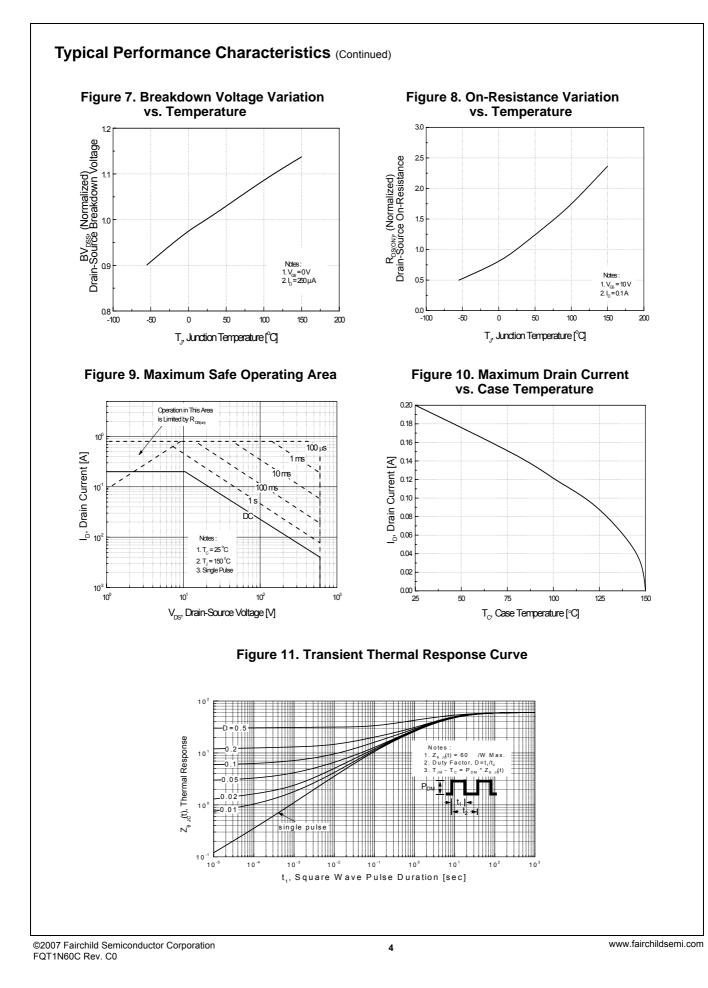
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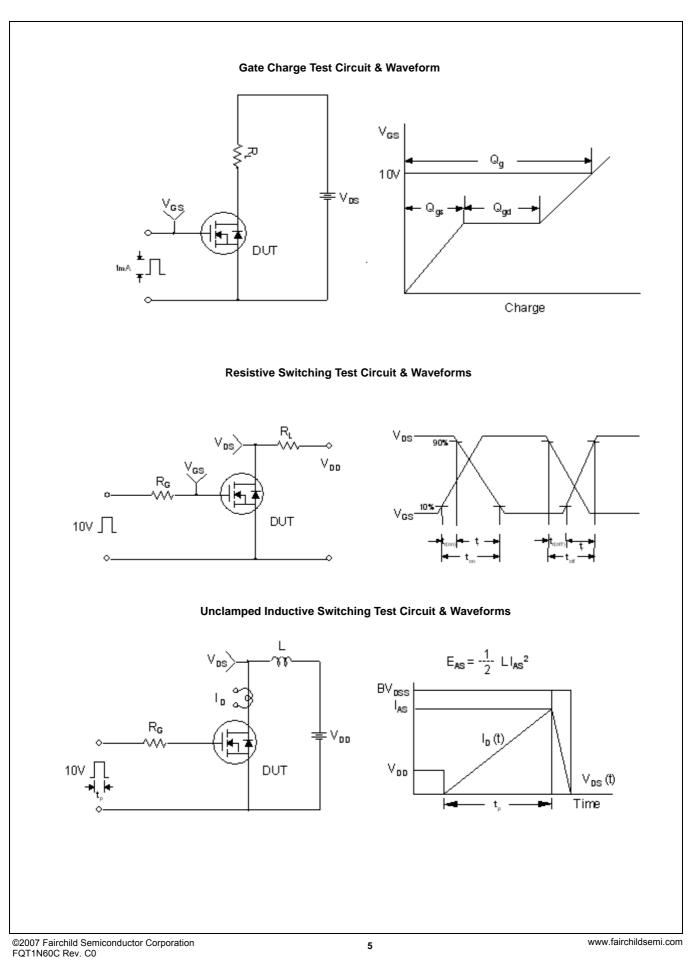
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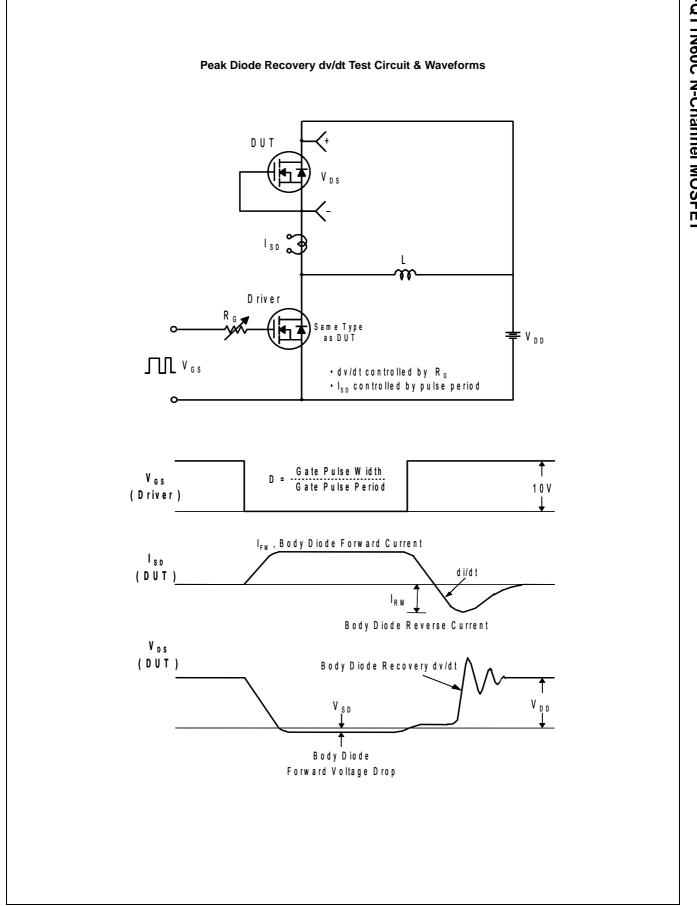
0

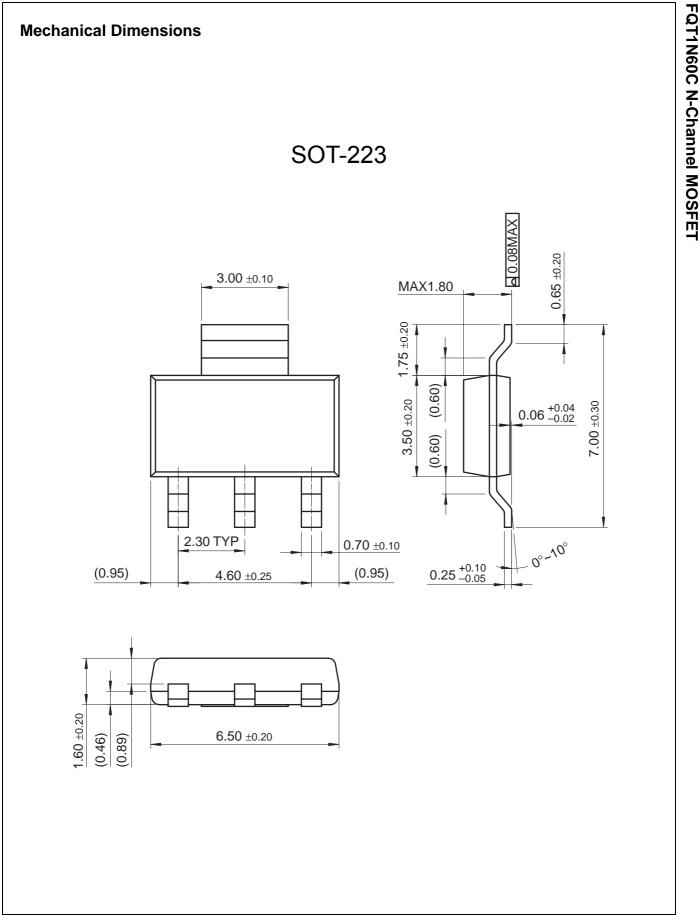
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